


**Features**

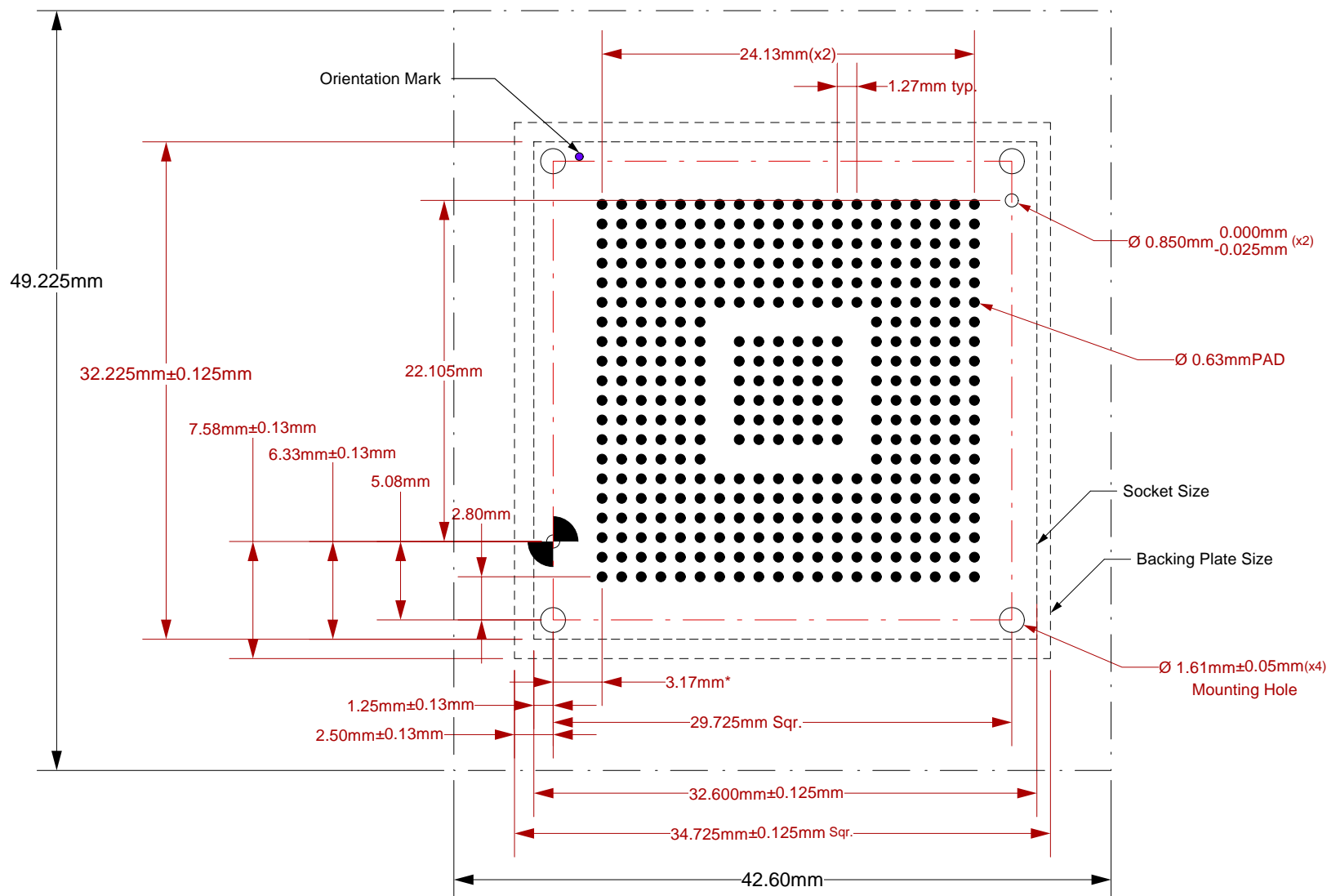
- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

**Materials:**

- △1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- △2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- △3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- △4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
- △5 Pogo Pin: Plungers - Hardened Steel/ Gold plated Barrel - Copper Alloy/ Gold plated Spring - Stainless Steel/ Gold wire
- △6 Pogo Pin Guides: Ultem 1000.
- △7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- △8 Backing Plate: Black anodized Aluminum
- △9 Insulation Plate: FR4/G10
- △10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- △11 Latch: Black anodized Aluminum.

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

 <p>© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p><b>SS-BGA372B-01 Drawing</b></p>	<p>Status: Released</p>	<p>Scale: 1.25:1</p>	<p>Rev: B</p>
	<p>Drawing: M.A.Fedde</p>	<p>Date: 7/28/06</p>		
	<p>File: SS-BGA372B-01 Dwg</p>	<p>Modified: 10/17/06</p>		



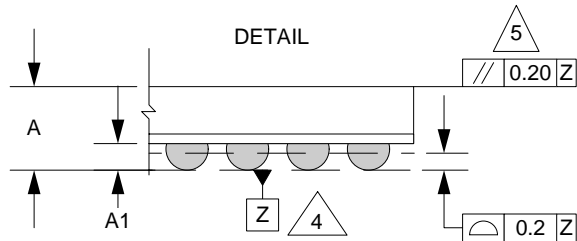
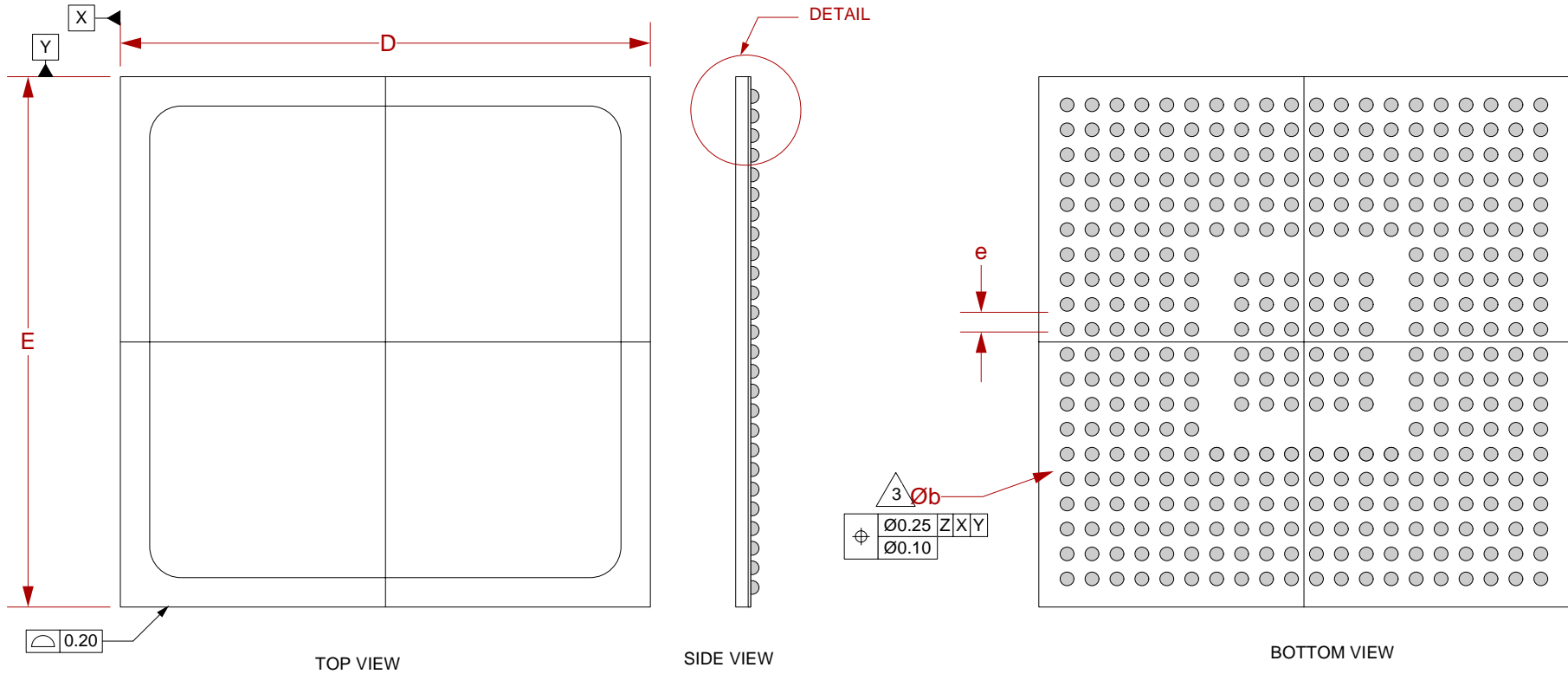
Target PCB Recommendations

Total thickness: 1.5mm min.

Plating: Gold or Solder finish

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


<p><b>SS-BGA372B-01 Drawing</b></p>	<p>Status: Released</p>	<p>Scale: 2.5:1</p>	<p>Rev: B</p>
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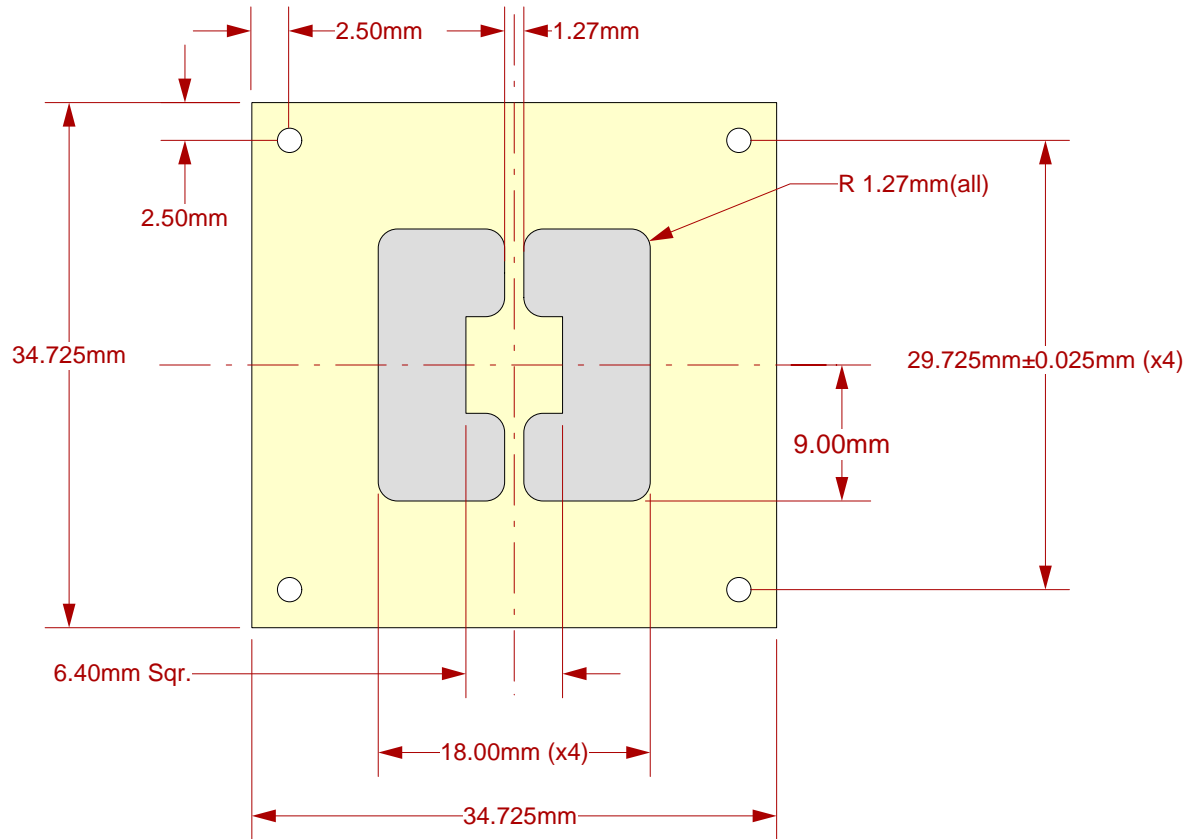
1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- △ 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - △ 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - △ 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.6
A1	0.5	0.7
b		0.90
D	27.00 BSC	
E	27.00 BSC	
e	1.27 BSC	

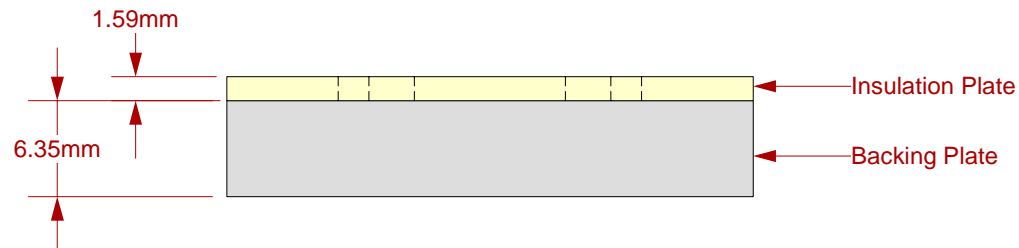
20x20 Array

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Top View




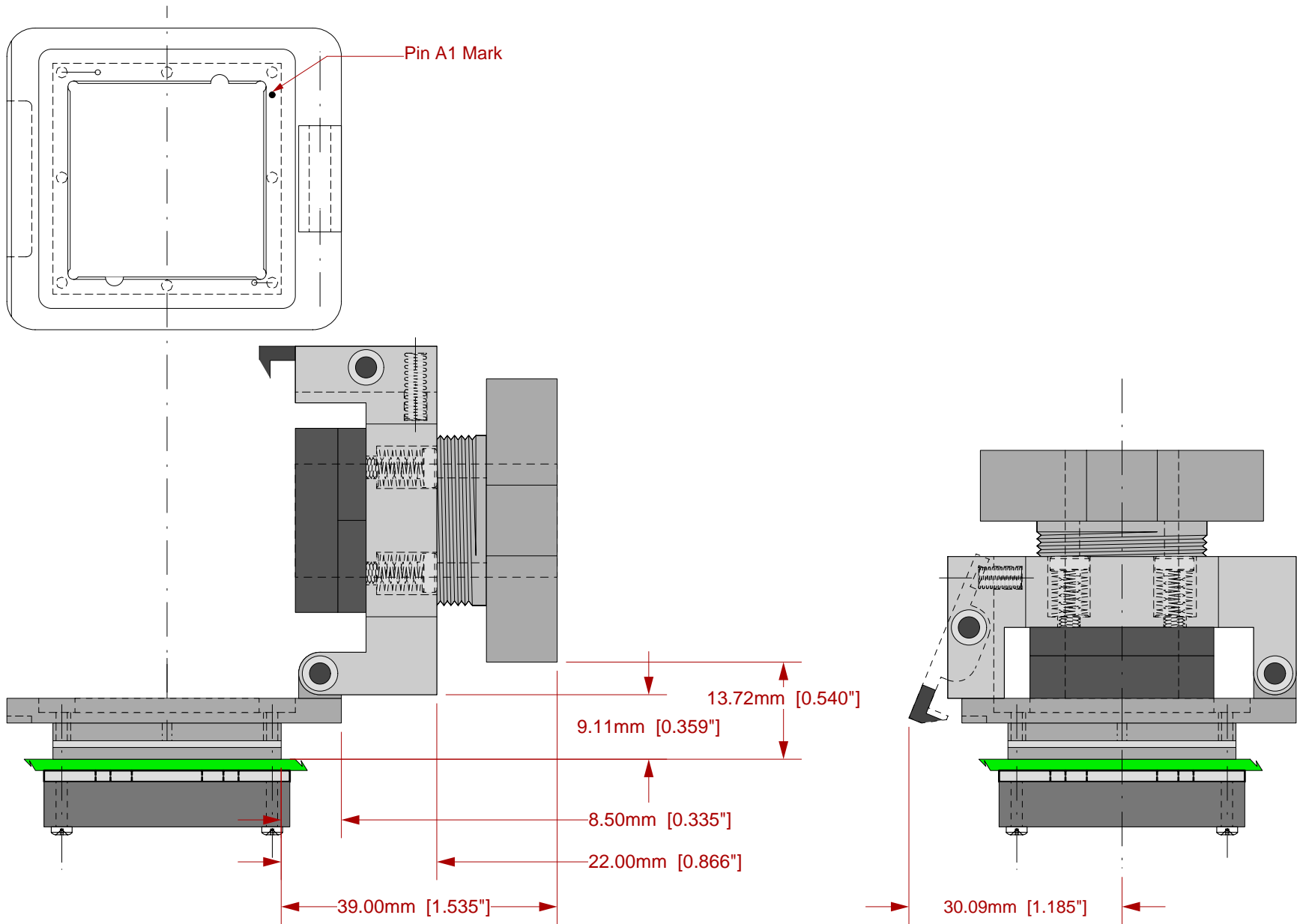
Side View




Description: Backing Plate with Insulation Plate

All dimensions are in mm.  
All tolerances are +/- 0.125mm.  
(Unless stated otherwise)

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